



Press Release

Unisem Unveils New Look

IPOH, 18 November 2005 – Unisem today unveils a new corporate logo and design. The dynamic, fresh and striking look will replace the 3 blue wafers 'U' logo that has served as Unisem's logo since 1991.

Unisem said the change accentuates the UNISEM name as a global brand and reflects the significant broadening of capabilities that occurred in recent years as the company expanded across the globe and introduced a portfolio of new products and services. The new logo and brand will project the significance of this change to our shareholders, customers, suppliers and employees.

"Unisem is a vastly different company today. Many people don't realize how much we've evolved," said Unisem Chairman and Managing Director John Chia. "Today we are bringing our look up to speed with our capabilities and identity."

Changing Unisem's visual identity may be one of the most significant corporate identity transformations in the company history. The visual changes will further communicate the global reach and expanding capabilities of Unisem. And while blue will no longer remain the primary color representing Unisem, the vibrant red with the complementary grey will be used for the corporate colors, and will become part of the design of the Unisem group's signage and buildings.

"Packaging and testing of semiconductors are and will remain the foundation of our business at Unisem," John Chia said. "But as we expand our capabilities and broaden the solutions we bring to our customers, we felt it was the right time to make our logo reflect the company's evolution."

For the past 2 years, Unisem has been developing and acquiring new capabilities to broaden the global Packaging and testing services it provides its customers. Today, Unisem offers an integrated suite of packaging and test services for semiconductor companies such as wafer probe, a wide range of leadframe and substrate IC packaging, high-end Radio Frequency and mix-signal testing, tape & reel and drop-shipment services. Unisem will also be offering Wafer Bumping services in the next 3 months under the joint venture with Advanpack Solutions Pte Ltd.

In addition, Unisem has expanded its presence in Europe through the acquisition of a packaging and testing facility in Wales. Last year, the company announced it would be providing semiconductor packaging and testing services in Chengdu, this represents an opportunity for Unisem to position itself in China.

About Unisem (www.unisem.com.my)

Unisem (M) Berhad, a leading semiconductor packaging and test services company in Malaysia, has its main packaging and testing facilities in Ipoh, Malaysia with additional packaging and testing facilities in Wales, United Kingdom. Unisem offers an integrated suite of packaging and test services for semiconductor companies such as wafer probe, a wide range of leadframe and substrate IC packaging, high-end RF and mix-signal test, tape & reel and drop-shipment services.